



# SOT480-1

plastic, thin shrink small outline package; 48 leads; 0.4 mm pitch; 9.7 mm x 4.4 mm x 0.9 mm body

30 January 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP48
<b>Package type industry code</b>	TSSOP48
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-153
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-2-2003
<b>Manufacturer package code</b>	SOT480

Table 1. Package summary

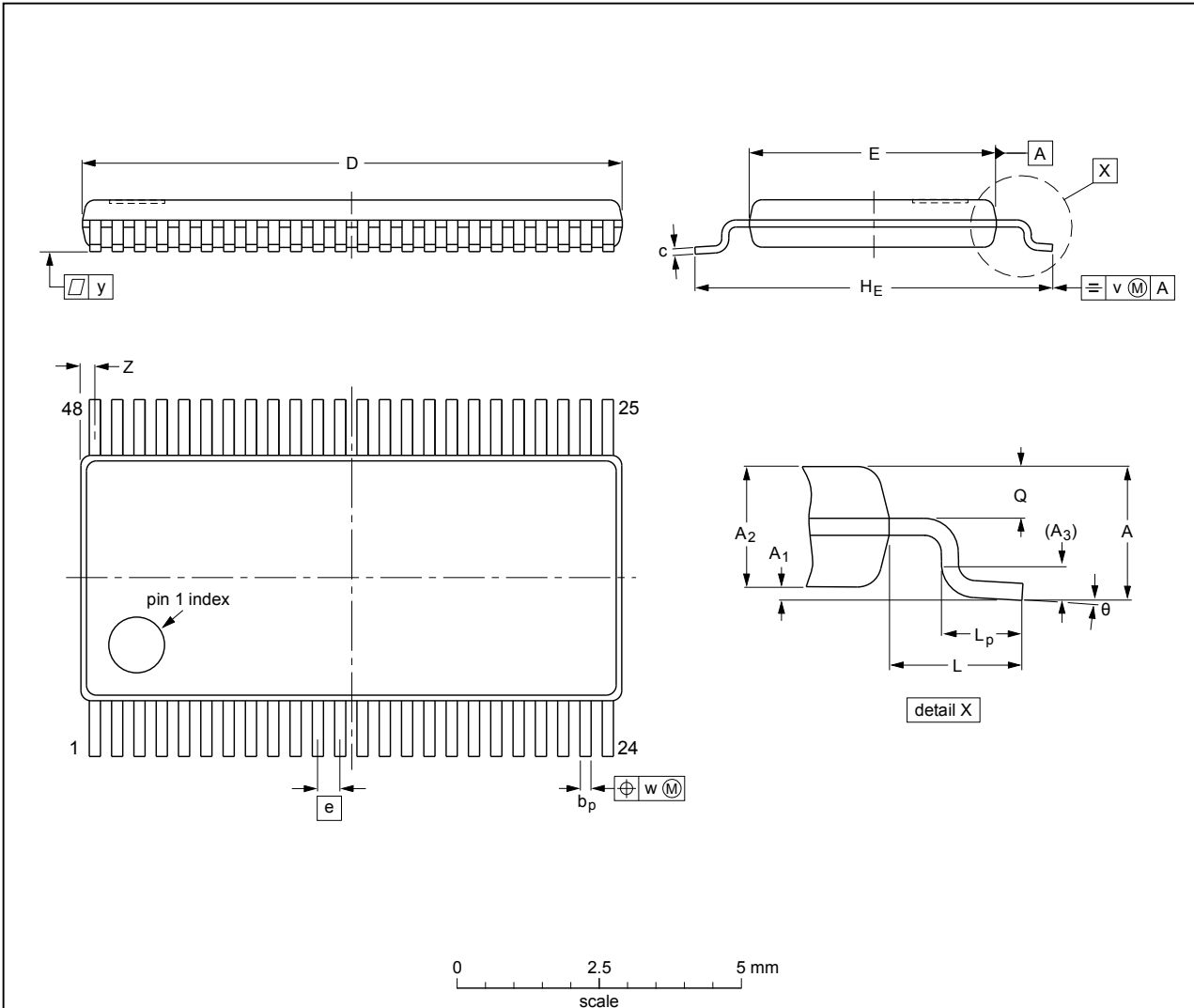
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.6	-	9.7	9.8	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	-	-	1.1	1.1	mm
A <sub>2</sub>	package height	0.85	-	0.9	0.95	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	

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## 2. Package outline

TSSOP48: plastic thin shrink small outline package; 48 leads;  
body width 4.4 mm; lead pitch 0.4 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.85	0.25	0.23 0.13	0.20 0.09	9.8 9.6	4.5 4.3	0.4	6.6 6.2	1	0.7 0.5	0.4 0.3	0.2	0.07	0.08	0.4 0.1	8° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT480-1		MO-153				99-12-27 03-02-18

Fig. 1. Package outline TSSOP48 (SOT480-1)

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### 3. Soldering

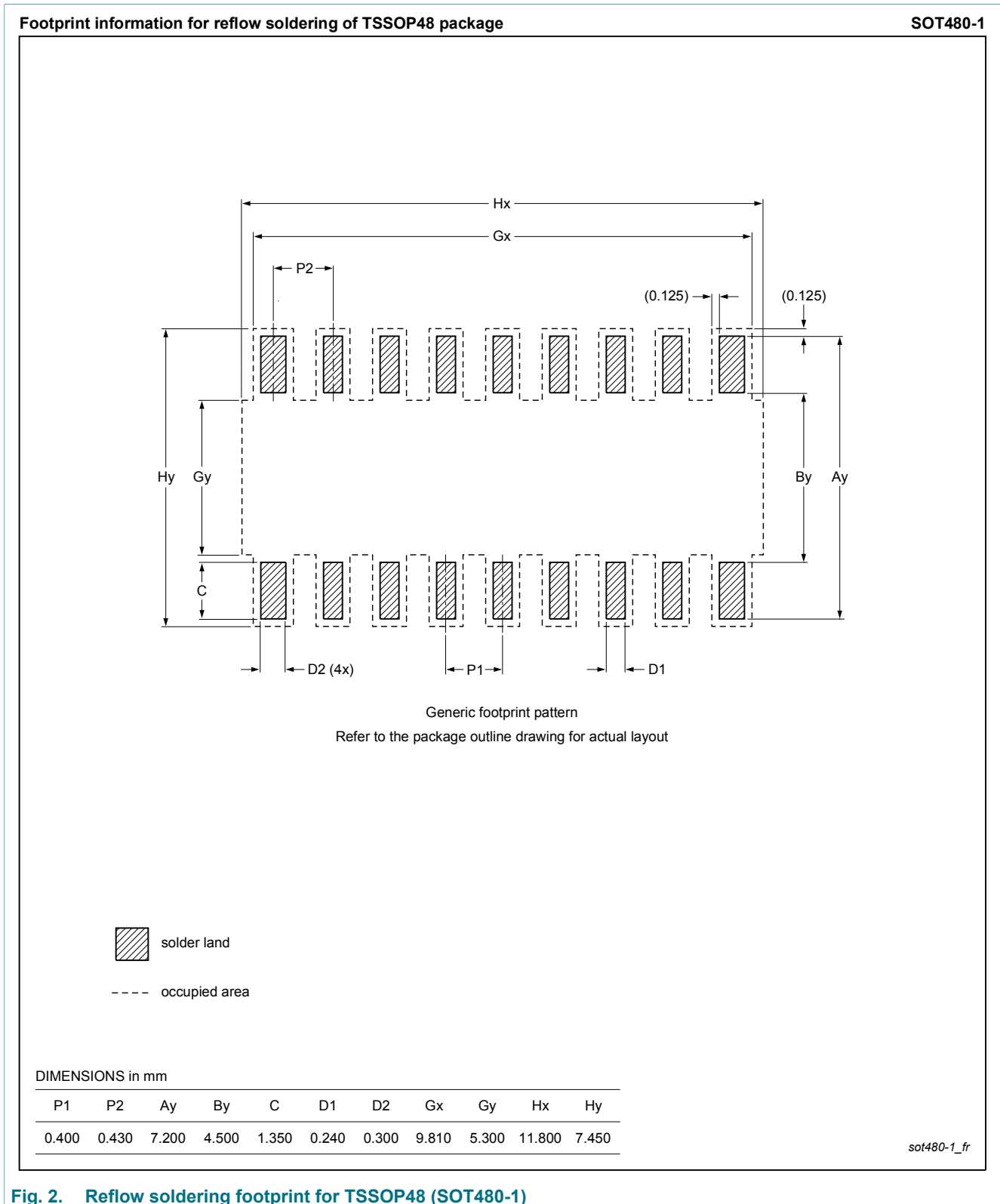


Fig. 2. Reflow soldering footprint for TSSOP48 (SOT480-1)

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## 4. Legal information

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